

SOT1222-1

plastic, heatsink small outline package; 6 leads

10 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP6
Package type industry code	HSOP6
Package style descriptive code	HSOP (heatsink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	2-7-2012

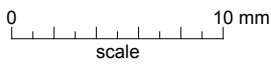
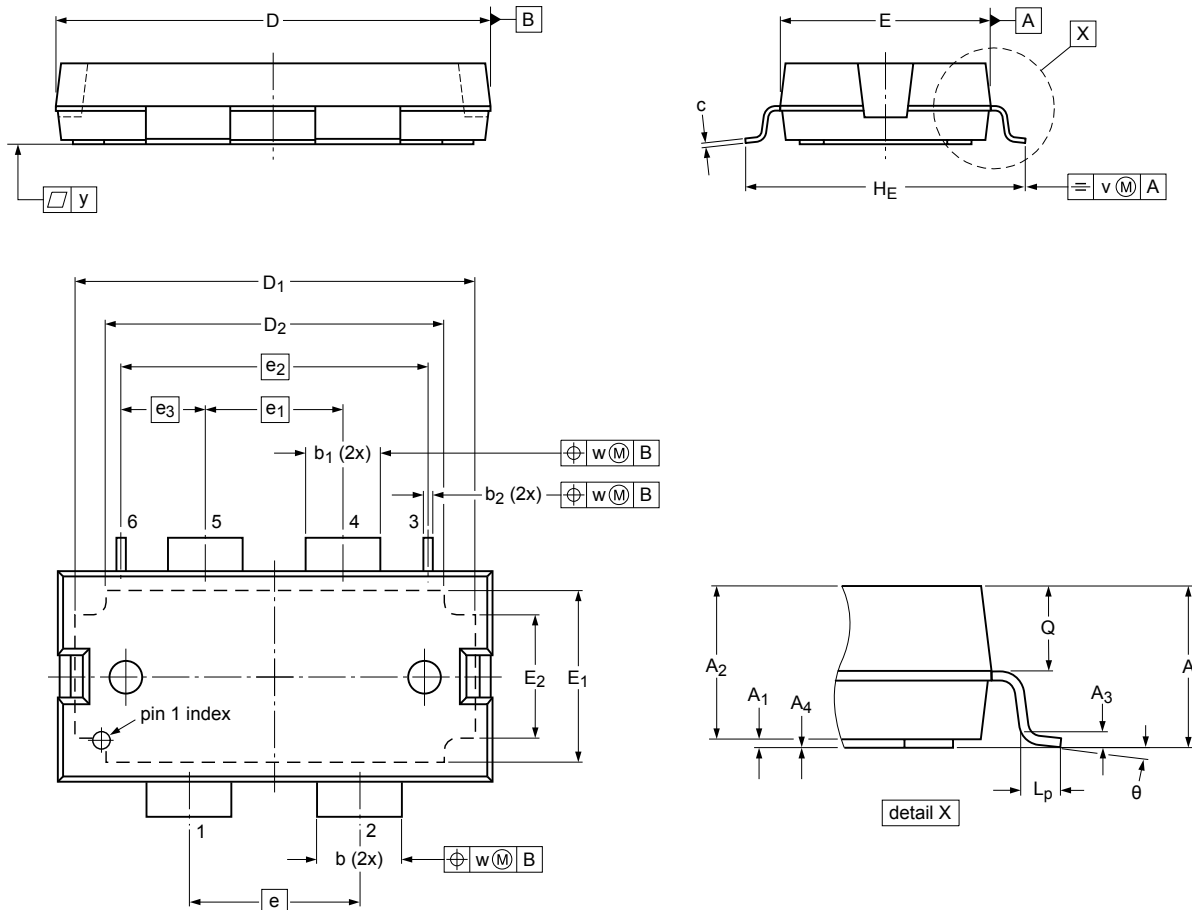
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	20.52	-	20.57	20.62	mm
E	package width	9.91	-	9.96	10.01	mm
A	seated height	-	-	-	3.9	mm
A ₂	package height	3.55	-	3.6	3.65	mm
e	nominal pitch	-	-	8	-	mm
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

HSOP6: plastic, heatsink small outline package; 6 leads SOT1222-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	A ₃	A ₄	b	b ₁	b ₂	c	D ⁽¹⁾	D ₁	D ₂	E ⁽¹⁾	E ₂	E ₃	e	e ₁	e ₂	e ₃	H _E	L _p	Q	
max	3.9	0.2	3.65		0.06	4.05	3.55	0.50	0.27	20.62	19.00	16.05	10.01	8.18	5.89						13.5	1.10	2.07
nom		0.1	3.60	0.35	0	4.00	3.50	0.45	0.22	20.57	18.95	16.00	9.96	8.13	5.84	8.0	6.5	14.5	4.0	13.2	0.95	2.02	
min		0	3.55		-0.02	3.95	3.45	0.40	0.17	20.52	18.90	15.95	9.91	8.08	5.79						12.9	0.80	1.97

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot1222-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
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Fig. 1. Package outline HSOP6 (SOT1222-1)

3. Legal information

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